



1 FIG-1 WITH MATED PLUG(1:1)

RECOMMENDED PC BOARD PATTERN  
APPLICABLE PC BOARD t=0.8~1.6

PANEL CUTOUT(2:1)  
(PANEL THICKNESS t=1.5 mm MAX)

2 FIG-2 SMT&COPLANARITY LEAD DIMENSIONS

NOTES 1 LOCK MARK ON PLUG IN MATED CONDISION IS AS SHOWN FIG-1.  
2 SMT LEAD DIMENSION FOR CONTACT (REF No. ③, ④) SHALL BE AS SHOWN IN THE FIG.2

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2μm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7μm MIN		4	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2μm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7μm MIN	
2	STAINLESS STEEL	LEAD UNDER : TIN COPPER PLATING 3μm MIN : NICKEL PLATING 2μm MIN		1	POLYAMIDE	OVER : TIN REFLOW PLATING 1μm MIN UNDER : NICKEL PLATING 0.2μm MIN	
1	POLYAMIDE	BLACK, UL94V-0					

  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
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